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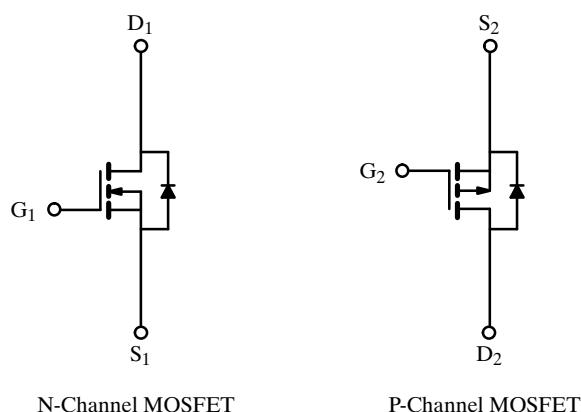
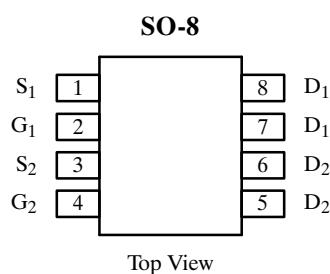
Siliconix

Si4532DY

Dual Enhancement-Mode MOSFET (N- and P-Channel)

Product Summary

	V_{DS} (V)	$r_{DS(on)}$ (Ω)	I_D (A)
N-Channel	30	0.065 @ $V_{GS} = 10$ V	± 3.9
		0.095 @ $V_{GS} = 4.5$ V	± 3.1
P-Channel	-30	0.085 @ $V_{GS} = -10$ V	± 3.5
		0.19 @ $V_{GS} = -4.5$ V	± 2.5



Absolute Maximum Ratings ($T_A = 25^\circ\text{C}$ Unless Otherwise Noted)

Parameter	Symbol	N-Channel	P-Channel	Unit
Drain-Source Voltage	V_{DS}	30	-30	V
Gate-Source Voltage	V_{GS}	± 20	± 20	
Continuous Drain Current ($T_J = 150^\circ\text{C}$) ^a	I_D	± 3.9	± 3.5	A
		± 3.1	± 2.8	
Pulsed Drain Current	I_{DM}	± 20	± 20	
Continuous Source Current (Diode Conduction) ^a	I_S	1.7	-1.7	
Maximum Power Dissipation ^a	P_D	2.0		W
		1.3		
Operating Junction and Storage Temperature Range	T_J, T_{Stg}	-55 to 150		°C

Thermal Resistance Ratings

Parameter	Symbol	N- or P-Channel	Unit
Maximum Junction-to-Ambient ^a	R_{thJA}	62.5	°C/W

Notes

a. Surface Mounted on FR4 Board, $t \leq 10$ sec.

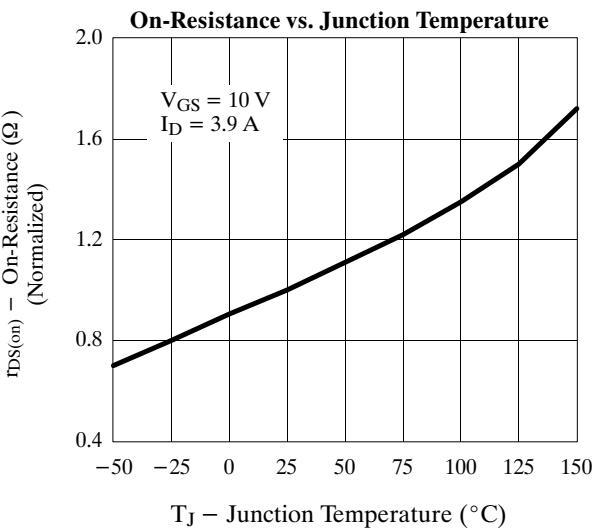
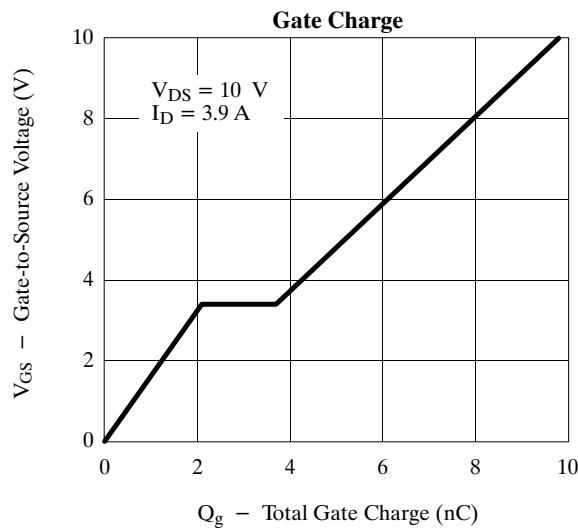
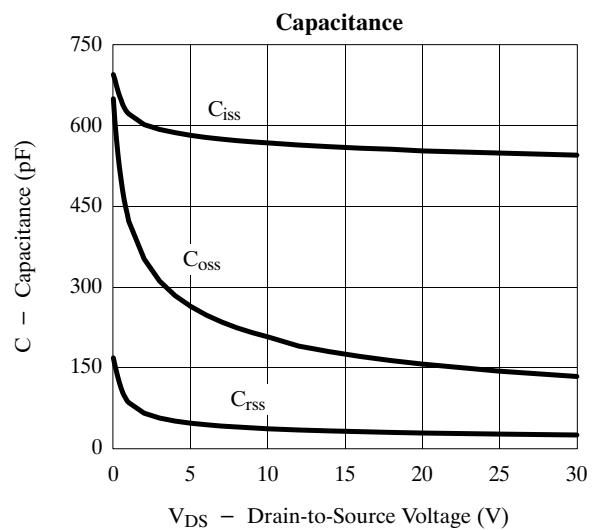
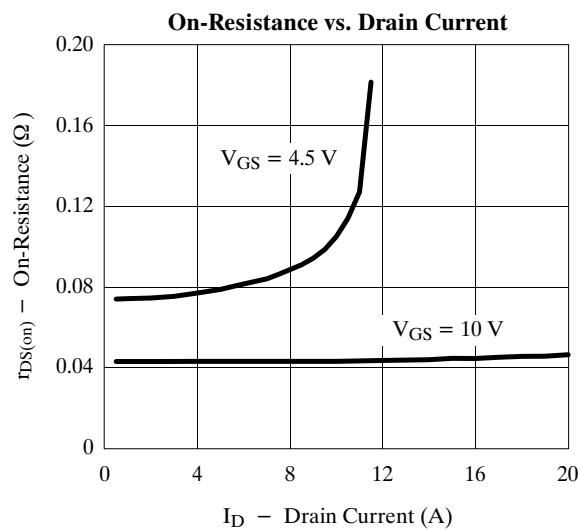
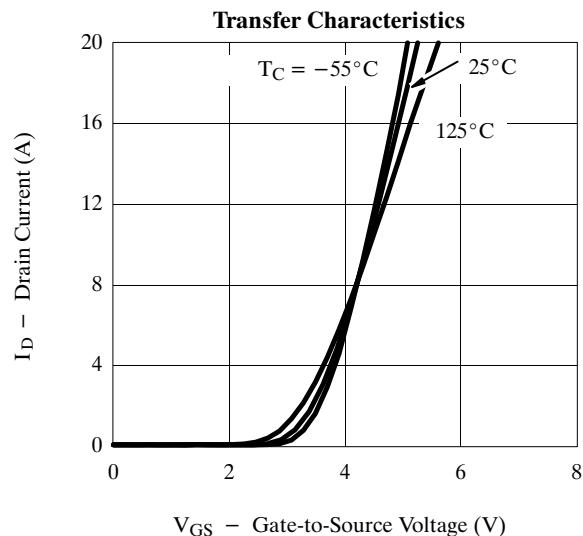
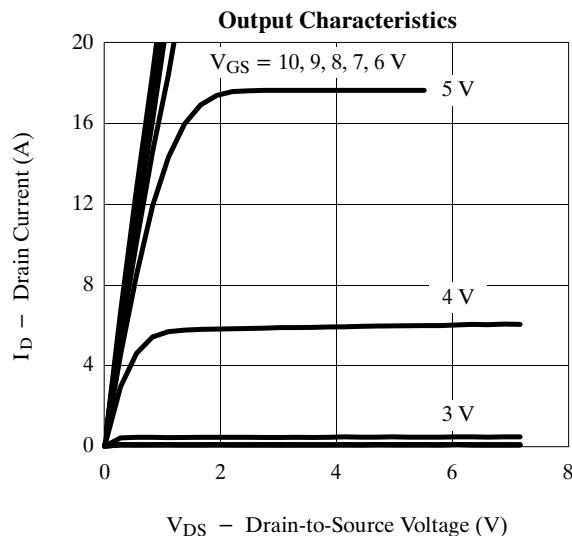
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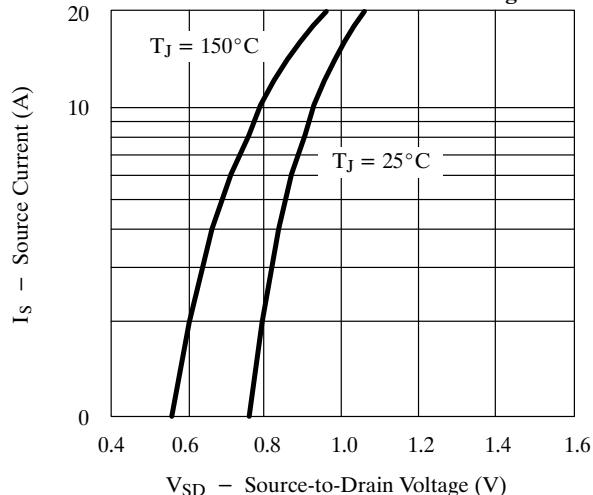
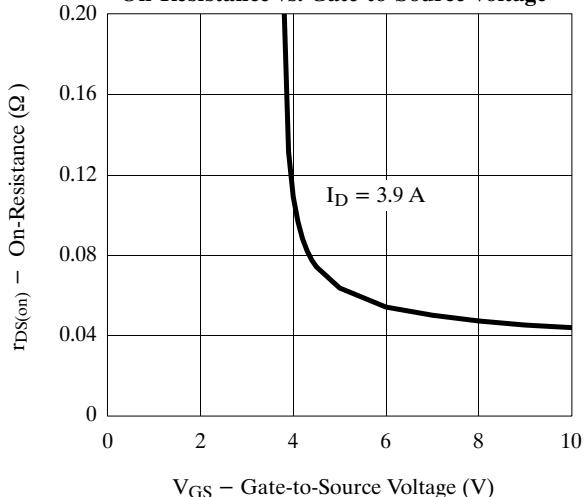
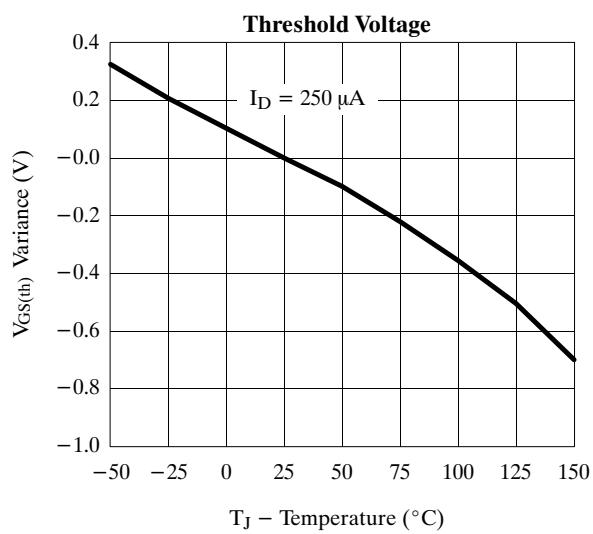
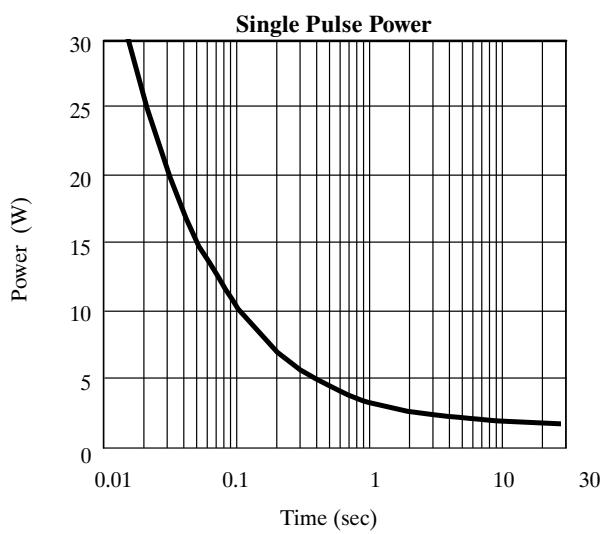
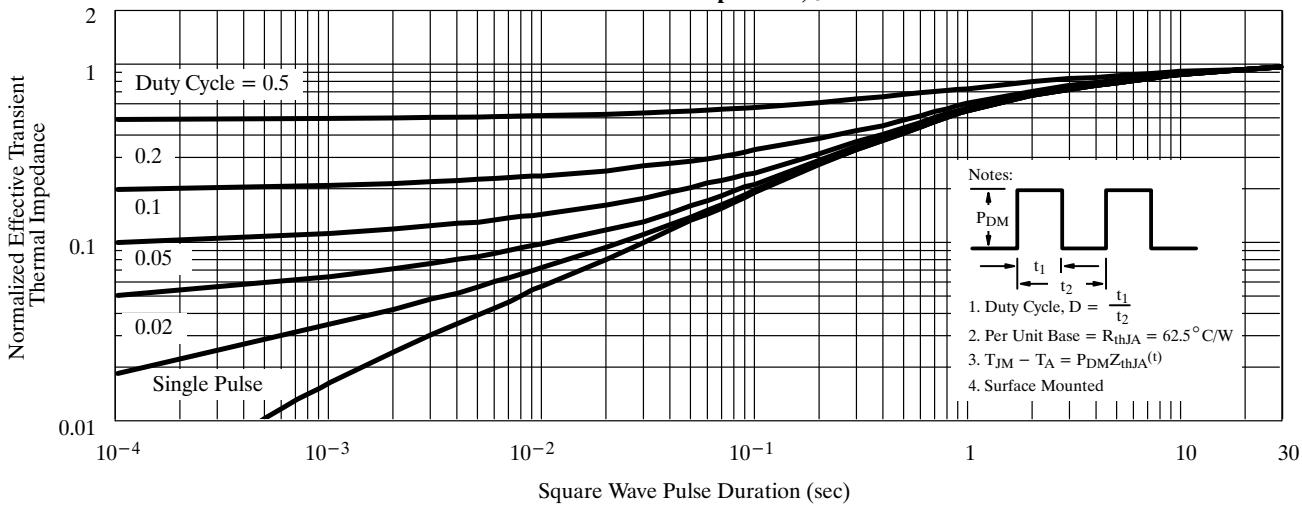
Specifications ($T_J = 25^\circ\text{C}$ Unless Otherwise Noted)

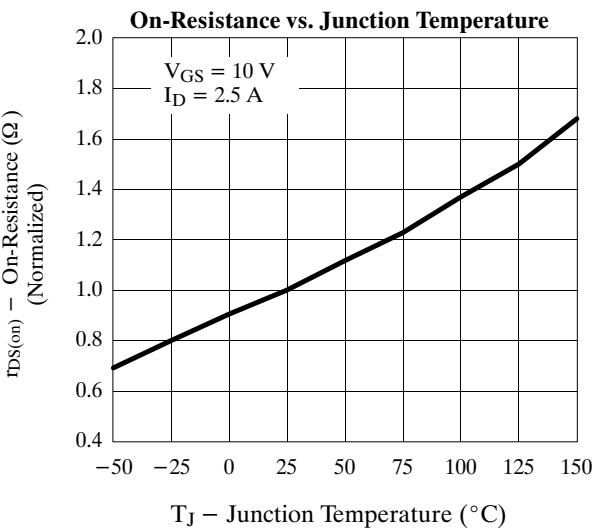
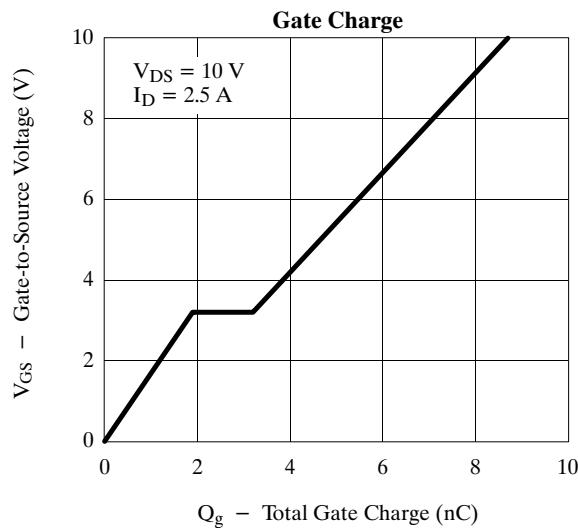
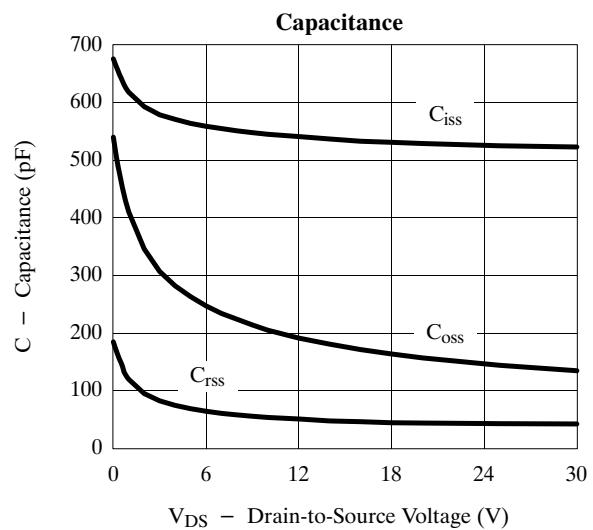
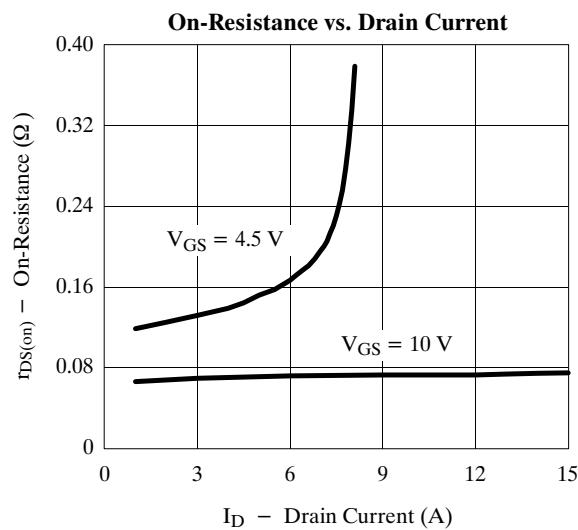
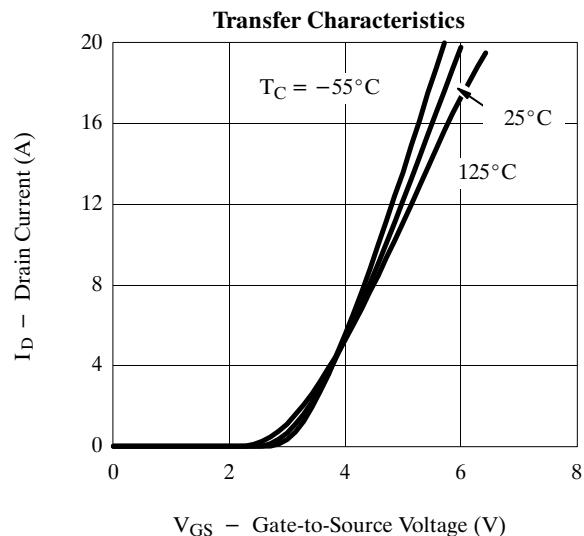
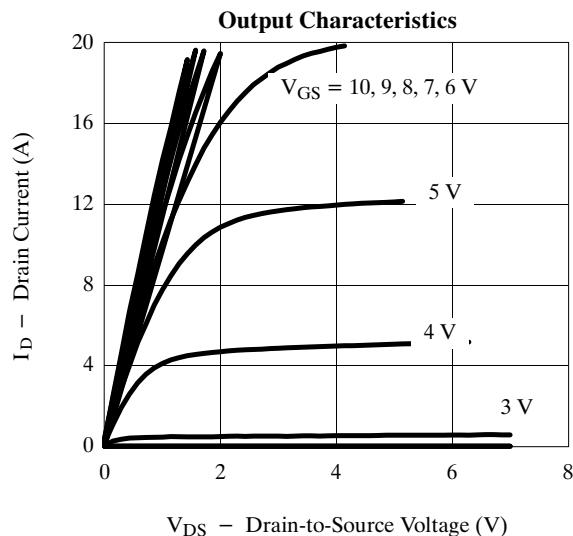
Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Static						
Gate Threshold Voltage	$V_{GS(\text{th})}$	$V_{DS} = V_{GS}, I_D = 250 \mu\text{A}$	N-Ch	1.0		
		$V_{DS} = V_{GS}, I_D = -250 \mu\text{A}$	P-Ch	-1.0		V
Gate-Body Leakage	I_{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$	N-Ch P-Ch		± 100 ± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{ V}$	N-Ch		1	
		$V_{DS} = -30 \text{ V}, V_{GS} = 0 \text{ V}$	P-Ch		-1	μA
		$V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{ V}, T_J = 55^\circ\text{C}$	N-Ch		25	
		$V_{DS} = -30 \text{ V}, V_{GS} = 0 \text{ V}, T_J = 55^\circ\text{C}$	P-Ch		-25	
On-State Drain Current ^a	$I_{D(\text{on})}$	$V_{DS} \geq 5 \text{ V}, V_{GS} = 10 \text{ V}$	N-Ch	15		A
		$V_{DS} \geq -5 \text{ V}, V_{GS} = -10 \text{ V}$	P-Ch	-15		
Drain-Source On-State Resistance ^a	$r_{DS(\text{on})}$	$V_{GS} = 10 \text{ V}, I_D = 3.9 \text{ A}$	N-Ch		0.043	0.065
		$V_{GS} = -10 \text{ V}, I_D = 2.5 \text{ A}$	P-Ch		0.066	0.085
		$V_{GS} = 4.5 \text{ V}, I_D = 3.1 \text{ A}$	N-Ch		0.075	0.095
		$V_{GS} = -4.5 \text{ V}, I_D = 1.8 \text{ A}$	P-Ch		0.125	0.19
Forward Transconductance ^a	g_{fs}	$V_{DS} = 15 \text{ V}, I_D = 3.9 \text{ A}$	N-Ch		7	
		$V_{DS} = -15 \text{ V}, I_D = -2.5 \text{ A}$	P-Ch		5	S
Diode Forward Voltage ^a	V_{SD}	$I_S = 1.7 \text{ A}, V_{GS} = 0 \text{ V}$	N-Ch		0.8	1.2
		$I_S = -1.7 \text{ A}, V_{GS} = 0 \text{ V}$	P-Ch		-0.8	-1.2
Dynamic^b						
Total Gate Charge	Q_g	N-Channel $V_{DS} = 10 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 3.9 \text{ A}$ P-Channel $V_{DS} = -10 \text{ V}, V_{GS} = -10 \text{ V}, I_D = -2.5 \text{ A}$	N-Ch		9.8	15
Gate-Source Charge	Q_{gs}		P-Ch		8.7	15
Gate-Drain Charge	Q_{gd}		N-Ch		2.1	
Gate-Drain Charge	Q_{gd}		P-Ch		1.9	
Turn-On Delay Time	$t_{d(\text{on})}$	N-Channel $V_{DD} = 10 \text{ V}, R_L = 10 \Omega$ $I_D \cong 1 \text{ A}, V_{GEN} = 10 \text{ V}, R_G = 6 \Omega$ P-Channel $V_{DD} = -10 \text{ V}, R_L = 10 \Omega$ $I_D \cong -1 \text{ A}, V_{GEN} = -10 \text{ V}, R_G = 6 \Omega$	N-Ch		1.6	
Rise Time	t_r		P-Ch		1.3	
Turn-Off Delay Time	$t_{d(\text{off})}$		N-Ch		9	15
Fall Time	t_f		P-Ch		7	15
Source-Drain Reverse Recovery Time	t_{rr}	$I_F = 1.7 \text{ A}, di/dt = 100 \text{ A}/\mu\text{s}$	N-Ch		6	18
		$I_F = -1.7 \text{ A}, di/dt = 100 \text{ A}/\mu\text{s}$	P-Ch		9	18

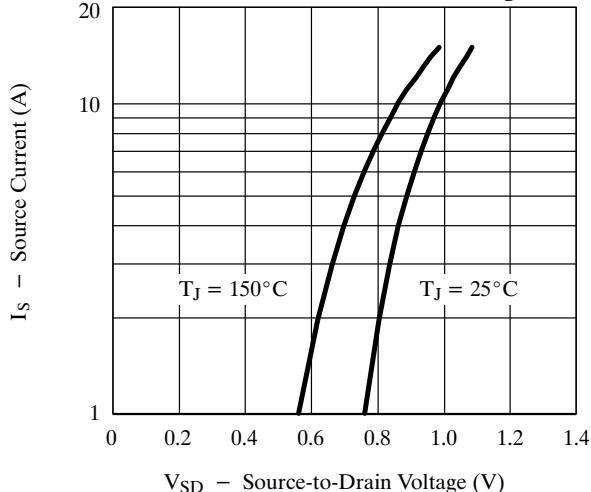
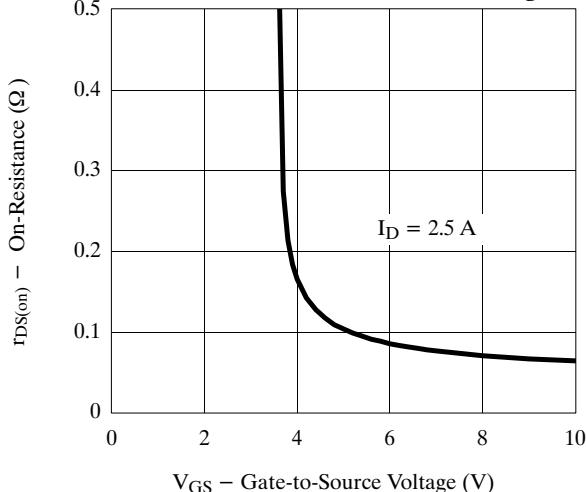
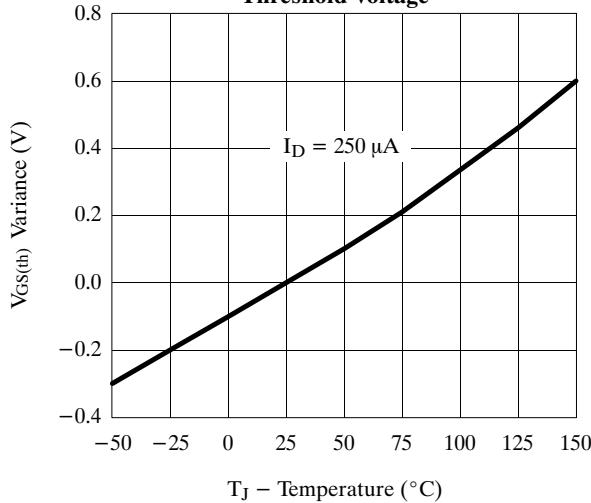
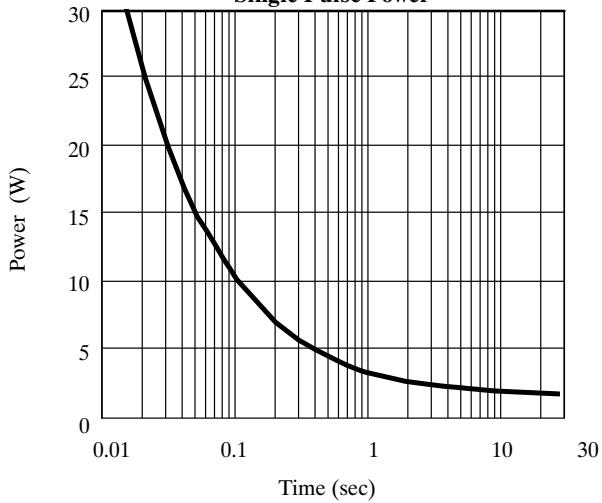
Notes

- a. Pulse test; pulse width $\leq 300 \mu\text{s}$, duty cycle $\leq 2\%$.
b. Guaranteed by design, not subject to production testing.

Typical Characteristics (25°C Unless Noted)**N-Channel**

Si4532DY**Typical Characteristics (25°C Unless Noted)****N-Channel****Source-Drain Diode Forward Voltage****On-Resistance vs. Gate-to-Source Voltage****Threshold Voltage****Single Pulse Power****Normalized Thermal Transient Impedance, Junction-to-Ambient**

Typical Characteristics (25°C Unless Noted)**P-Channel**

Si4532DY**Typical Characteristics (25°C Unless Noted)****P-Channel****Source-Drain Diode Forward Voltage****On-Resistance vs. Gate-to-Source Voltage****Threshold Voltage****Single Pulse Power****Normalized Thermal Transient Impedance, Junction-to-Ambient**